

IN THE CLAIMS:

Please cancel claims 12 and 17-35.

Please amend claims 3-6, 13 and 14-16 as follows:

A1
3. (Amended once) The separator plate [as defined in either] of [claims 1 or 2] claim 1, wherein the traces are metallic.

4. (Amended once) The separator plate [as claimed in claims 1 - 3] of claim 3, wherein all metallic surfaces are covered with an inert coating.

5. (Amended once) The separator plate [as claimed in claims 1, 2 or 4] of claim 1, wherein the MEA structures are mechanically connected to said conductive traces.

6. (Amended once) The separator plate [as claimed in any] of [claims 1 - 4] claim 1, wherein said traces are formed on and constitute part of a printed circuit board.

A2
~~12~~
13. (Amended once) The separator plate [as claimed in] of claim [11] 5, wherein the said MEA structure is soldered to the said traces.

~~13~~
14. (Amended once) The separator plate [as claimed in any] of [claims 1-13] claim 1, wherein said substrate is non-planar.